



05-25-08

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Eric NEYRET et al.

Confirmation No.: 1763

Application No: 10/750,443

Group Art Unit: 2818

Filing Date: December 30, 2003

Examiner: Phuc T. Dang

For: METHOD FOR REDUCING FREE SURFACE
ROUGHNESS OF A SEMICONDUCTOR WAFER

Atty. Docket No.: 4717-8300

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

In response to the Office Action dated May 6, 2005, Applicants respectfully request the entry of the following amendments and comments into the file of this application.

AMENDMENTS TO THE CLAIMS begin on page 2.

REMARKS begin on page 6.

No fees are believed to be due for this submission. Should any fees be required, however, please charge such fees to Winston & Strawn LLP Deposit Account No. 50-1814.